


Full Material Declaration for attached parts list

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	<p>Diotech Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 May 2009 [Approved: 05 February 2024 14:54 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	1.09%	Silicon	7440-21-3	100%
			Carbon black	1333-86-4	0.7%
			ZINCITE (MINERAL)	1314-13-2	0.8%
			Melamine isocyanurate	37640-57-6	1%
Encapsulation	EP (Epoxy resin)	74%	Boron zinc hydroxide oxide	138265-88-0	3.5%
			Phenol, polymer with formaldehyde	9003-35-4	9%
			Silicon Dioxide	7631-86-9	85%
			Gold	7440-57-5	100%
Inner preparation	Gold	0.15%	Gold	7440-57-5	100%
Leadfinish	Tin plating	0.74%	Tin	7440-31-5	100%
			Copper	7440-50-8	0.168%
Leadframe	Steel and iron materials	24.02%	SILVER, ELEMENTAL	7440-22-4	1.196%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.636%

Attached parts list

Part number	Part name
SOD-323_PbF_HF_Au	Diode SMD